SEMTECH

PROTECTION PRODUCTS - Z-Pak™

Description

µClamp[®] TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace 0201 size multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. They features large cross-sectional area junctions for conducting high transient currents. These devices offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

µClamp[®]3311Z is constructed using Semtech's proprietary EPD process technology. The EPD process provides low standoff voltages with significant reductions in leakage currents and capacitance over silicon-avalanche diode processes. They feature a true operating voltage of 3.3 volts for superior protection when compared to traditional pn junction devices.

 μ Clamp3311Z is in a 2-pin SLP0603P2X3A package. It measures 0.6 x 0.3 mm with a nominal height of only 0.25mm. Leads are finished with lead-free NiAu. Each device will protect one line operating at 3.3 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Features

- High ESD withstand Voltage: +/-14kV (Contact) and +/- 16kV (Air) per IEC 61000-4-2
- Able to withstand over 1000 ESD strikes per IEC 61000-4-2 Level 4
- Ultra-small 0201 package
- Protects one data line
- Low reverse current: <10nA typical (VR=5V)</p>
- Working voltage: +/- 3.3V
- Low capacitance: 6pF typical
- Extremely low dynamic resistance: 0.21 Ohms (Typ)
- Solid-state silicon-avalanche technology

Mechanical Characteristics

- SLP0603P2X3A package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- Lead Finish: NiAu
- Marking : Marking code
- Packaging : Tape and Reel

Applications

- Cellular Handsets & Accessories
- Keypads, Side Keys, Audio Ports
- Portable Instrumentation
- Digital Lines
- Tablet PC

Nominal Dimensions



Schematic



ЛТЕСН

PROTECTION PRODUCTS

Absolute Maximum Rating						
Rating	Symbol	Value	Units			
Peak Pulse Power (tp = 8/20µs)	P _{pk}	30	Watts			
Maximum Peak Pulse Current (tp = 8/20µs)	l _{pp}	4	Amps			
ESD per IEC 61000-4-2 $(Air)^{1}$ ESD per IEC 61000-4-2 $(Contact)^{1}$	V _{ESD}	+/- 16 +/- 14	kV			
Operating Temperature	T,	-40 to +85	°C			
Storage Temperature	T _{stg}	-55 to +150	°C			

Electrical Characteristics (T=25°C)

			-			_
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}				3.3	V
Punch-Through Voltage	V _{PT}	Ι _{ΡΤ} = 50μΑ	3.65	4	4.4	V
Snap-Back Voltage	V _{SB}	I _{sb} = 50mA	2.8			V
Reverse Leakage Current	I _R	V _{RWM} = 3.3V		0.001	0.05	μA
Clamping Voltage	V _c	I _{PP} = 1A, tp = 8/20μs			5.5	V
Clamping Voltage	VC	I _{PP} = 3A, tp = 8/20μs			6.5	V
Clamping Voltage	V _c	I _{PP} = 4A, tp = 8/20μs			7.5	V
Dynamic Resistance ^{2, 3}	R _D	tp = 100ns		0.21		Ohms
Junction Capacitance	C _j	I/O pin to Gnd V _R = OV, f = 1MHz		6	9	pF

Notes

1)ESD gun return path connected to ESD ground reference plane.

2)Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$. 3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$



Typical Characteristics

Non-Repetitive Peak Pulse Power vs. Pulse Time



Normalized Junction Capacitance vs. Reverse Voltage



ESD Clamping (+8kV Contact per IEC 61000-4-2)





Clamping Voltage vs. Peak Pulse Current (tp=8/20us)

TLP Characteristic









Applications Information

Device Connection Options

The μ Clamp3311Z is designed to protect one data line operating up to 3.3 volts. It will present a high impedance to the protected line up to 3.3 volts. It will "turn on" when the line voltage exceeds 3.5 volts. The device is bidirectional and may be used on lines where the signal polarity is above and below ground. These devices are not recommended for use on DC power supply lines due to their snap-back voltage characteristic.

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.

Assembly Parameter	Recommendation	
Solder Stencil Design	Laser cut, Electro-polished	
Aperture shape	Rectangular with rounded corners	
Solder Stencil Thickness	0.100 mm (0.004")	
Solder Paste Type	Type 4 size sphere or smaller	
Solder Reflow Profile	Per JEDEC J-STD-020	
PCB Solder Pad Design	Non-Solder mask defined	
PCB Pad Finish	OSP OR NiAu	



Recommended Mounting Pattern





Outline Drawing - SLP0603P2X3A



Land Pattern - SLP0603P2X3A





Marking Code



Notes:

1)Dots represent date code matrix and Pin 1 location

Ordering Information

Ordering Number	Qty per Reel	Carrier Tape	Reel Size	Comments
uClamp3311Z.TNT	10,000	Plastic	7 Inch	Not Recommended for New Designs
uClamp3311Z.TFT	15,000	Paper	7 Inch	
uClamp3311Z.TVT	50,000	Paper	13 Inch	

Notes:

1) MicroClamp, uClamp and $\mu Clamp$ are trademarks of Semtech Corporation

Device Orientation in Tape



uClamp3311Z



PROTECTION PRODUCTS

Carrier Tape Specification

Plastic Tape





Note: All dimensions in mm unless otherwise specified



Contact Information

Semtech Corporation Protection Products Division 200 Flynn Rd., Camarillo, CA 93012 Phone: (805)498-2111 FAX (805)498-3804